



Lead-Free Solder Paste

PF629-P214

Rev. 2019/01/09 Ver.01-02

BASIC OVERVIEW



SnAg0.3Cu0.7 Solder Paste
No Clean
Zero Halogen
Low Silver Content

APPLICATIONS

The Solder Paste is Intended for Industrial Use Only
Universal Lead-Free SMD Solder Paste
Wide Range of Applications and PCB designs

SPECIFICATION

Appearance	Gray paste w/o visible foreign and clusters	
Alloy Composition	Sn/Ag0.3/Cu0.7	JIS-Z-3282
Melting Point	217~226 °C	
Particle Size	(Type 3) 20µm - 45µm (Type 4) 20µm - 38µm (Type 5) 15µm - 25µm	J-STD-005
Powder Shape	Spherical	
Flux Content	11.5 ± 1.0 wt%	JIS-Z-3197
Viscosity	170 ± 30 Pa.s (25±1°C, 10rpm, Malcom)	JIS-Z-3284
Flux Type	ROLO	J-STD-004

ALLOY COMPOSITION

(Sn)	(Ag)	(Cu)	(Ni)	(Ge)	(Pb)	(Sb)	(Bi)	(Cd)	(Au)	(In)	(Al)	(As)	(Fe)	(Zn)
REM.	0.2~ 0.4	0.5~ 0.9	0~ 0.01	0~ 0.01	0.05 MAX	0.05 MAX	0.06 MAX	0.002 MAX	0.05 MAX	0.10 MAX	0.001 MAX	0.03 MAX	0.02 MAX	0.001 MAX

Patent No.: U.S Patent No. 6179935B1, Germany Patent No.19816671C2

(wt%)



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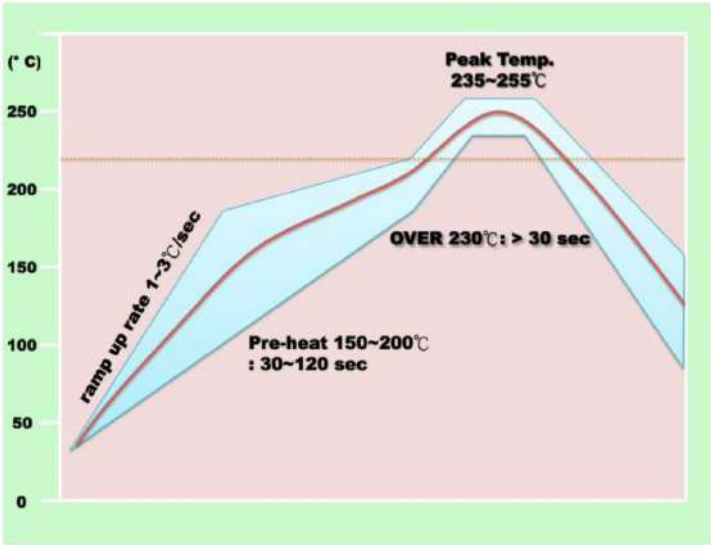
PERFORMANCE & RELIABILITY

Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Halogen Content Test	ROLO	BS EN14582
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C,10 rpm)	170 ± 30 Pa.s	JIS-Z-3284
Spreading Test	> 70%	JIS-Z-3197
Tackiness Test (gf)	> 130 (8hr)	JIS-Z-3284
Slump Test	Pass	JIS-Z-3284
Solder Ball Test	Pass	JIS-Z-3284

S.I.R. Test	▲	Pass	IPC-TM-650, 2.6.3.7
Electro Migration Test	◆	Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions: 40°C, 90% RH for 168hrs ◆ Test Conditions: 65°C, 88.5% RH for 596 hrs

RECOMMENDED REFLOW PROFILE



- Ramp Up Rate (30-150°C): 1.0-3.0°C/s
- Pre-heating Time (150-200°C): 30-120s
- Time Period Above 230°C: >30s
- Peak Temperature: 235-255°C
- Ramp Down Cooling Rate: 1.0-6.0°C/s

Notes:

- The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.
- For solder paste with powder size Type 4.5 or smaller, nitrogen atmosphere is strongly recommended for best soldering result.



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STORAGE & HANDLING:

- Refrigerate solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away from direct sunlight.
- Allow paste to reach ambient temperature (22-28°C) prior to use for 3-4 hrs. Do not heat up solder paste abruptly.
- Well mix paste with plastic spatula for 1min before use (jars packaging).
- It is recommended to finish fresh paste within 24 hrs. To maintain paste quality, make sure not to store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hr, remove the remained paste from the stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.
- To clean up printed circuit boards, it is suggested to use ethanol or isopropanol.

Note: For more information, please refer to solder paste application guideline sheet

HOW TO ORDER

PF629 – P214 – T4 – 500

Solder Alloy	Flux	Particle Size	Weight / Packaging
PF629 = SnAg0.3Cu0.7	P214 = ROL0	T3 = 20-45µm	30 = syringe 30g
		T4 = 20-38µm	100 = syringe 100g
		T5 = 15-25µm	150 = syringe 150g
			250 = plastic jar 250g
			500 = plastic jar 500g
			600 = small cartridge 600g
			1200 = large cartridge 1200g



CONTACTS

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